

## QCIOT-DA7212EVZ

Click Board™

### Description

The QCIOT-DA7212EVZ Click Board™ demonstrates the functionality and performance of the DA7212. The DA7212 is an ultra-low power audio codec targeting portable audio devices. The input paths support stereo FM line input and up to four analog (or two analog and two digital) microphones with two independent microphone biases. Comprehensive analog mixing and bypass paths to the output drivers are available.

The headphone output is true-ground Class G with integrated charge pump. There is also a differential Class AB speaker driver that can serve as a mono lineout.

Digital audio transfer to/from the external processor is via a bi-directional digital audio interface that supports all common sample rates and formats. The device may be operated in slave (target) or master (controller) modes using the internal PLL, which may be bypassed if not required. To fully optimize each customer application, a range of built-in filtering, equalization and audio enhancements are available. These are accessible by the processor over the I<sup>2</sup>C serial interface

### Kit Contents

- QCIOT-DA7212EVZ Click Board

### Features

- 100dB SNR stereo audio playback into 16Ω headphones
- 3.1mW power consumption for stereo DAC to headphone playback
- 1.2W mono speaker driver
- 650μW mono voice recorder
- Stereo digital microphone support
- Supports up to four analog microphones
- Two low-noise microphone-bias outputs
- Low-power PLL provides system clocking and audio sample rate flexibility
- Built-in 5-band equalizer, ALC and noise-gate functions
- Built-in beep generator
- Integrated system controller to eliminate pops and clicks
- Minimized external component count
- 34-ball WLCSP (4.54 × 1.66 mm) package
- Staggered 0.5 mm pitch for easy PCB routing allowing low-cost manufacture

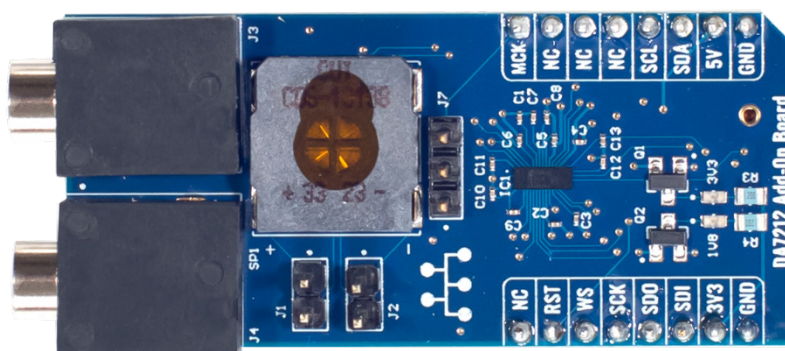


Figure 1. QCIOT-DA7212 Click Board

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# 1. Functional Description

The QCIOT-DA7212EVZ Click board is intended as a quick connect prototyping solution for DA7212. [Figure 2](#) highlights the main parts of the system.

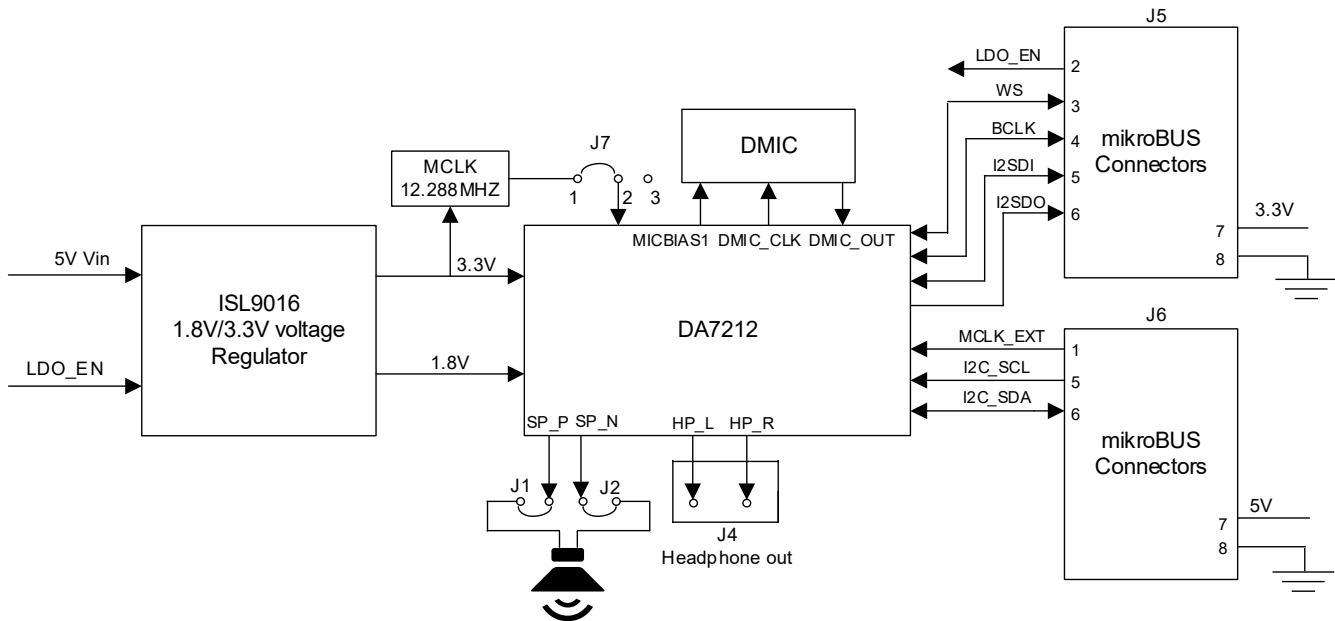


Figure 2. QCIOT-DA7212EVZ Click Board Block Diagram

## 1.1 Setup and Configuration

Required or recommended user equipment:

- Renesas Evaluation Board: [EK-RA2L1](#)
- USB micro-B cable (provided with RA board)
- PC running Windows 10/11 with at least two USB ports.
- QCIOT-DA7212EVZ Click board
- Micro-SD card reader Pmod
- Micro-SD card
- UART connection to the MCU

Required or recommended software:

- [Renesas Flexible Software Package \(FSP\)](#) v5.9.0 platform installation
  - Renesas [e² studio](#) 2025-04 or later
  - FSP 5.9.0 or later
  - GCC Arm Embedded 13.3.1 or later
- Sample code files (available on [QCIOT-DA7212EVZ webpage](#))

### 1.1.1 Software Installation

Visit the [e² studio](#) webpage for the latest version of the installer software.

### 1.1.2 Kit Hardware Connections

Follow these procedures to set up the kit (see [Figure 3](#)).

1. Ensure that the MCU development kit supports mikroBUS-type connector.
  - a. For EK-RA2L1, mikroBUS connector is available.
2. On the QCIOT-DA7212EVZ board, populate J1, J2, J7 (Pin 1 and 2) with jumpers to use on-board speaker. To play audio via Headphone (J4), populate only pins 1 and 2 of J7 with jumper and leave the rest open.
3. Ensure the EK-RA2L1 has the cyberon DSpotter license installed. To install the DSpotter license, refer to section 5 of the QCIOT-DA7212EVZ application note.
4. Plug in the QCIOT-DA7212EVZ board to the mikroBUS connector of EK-RA2L1. Ensure to align Pin 1 of J5 and J6 on QCIOT-DA7212EVZ and MCU kit pin 1 of J21 and J22.
5. Connect the EK board to the computer with a USB micro-B cable.
6. Connect the Micro SD card using Pmod Micro SD card reader to PMOD2 on the MCU kit.
7. Connect the USB to TTL, RX to P302 on EK-RA2L1, TX to P301 on EK-RA2L1 and ground.
8. The device is now ready to be used in the system.

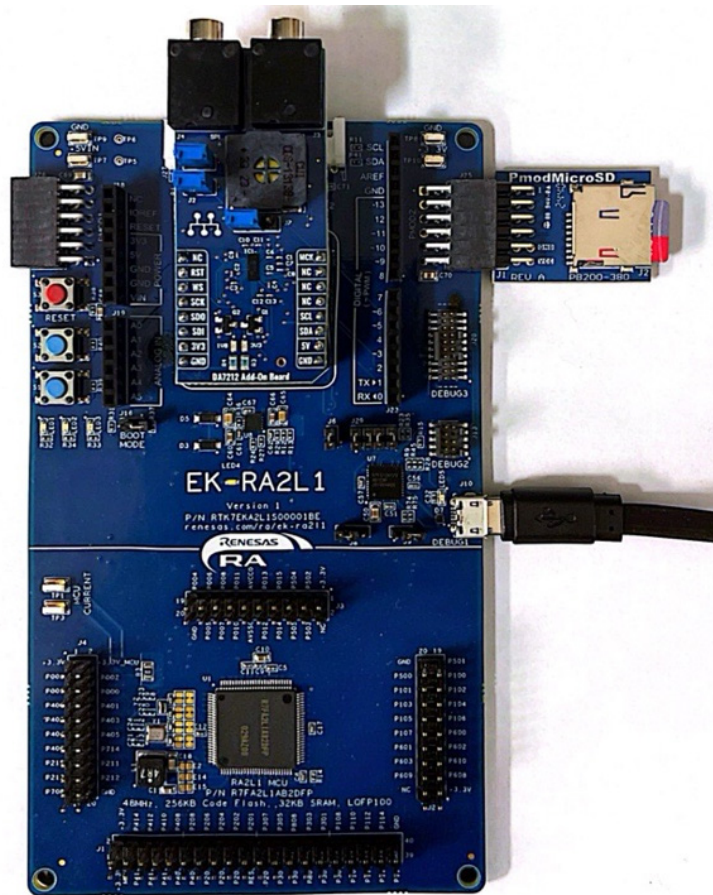


Figure 3. QCIOT-DA7212EVZ Click Board with EK-RA2L1 MCU

## 2. Board Design

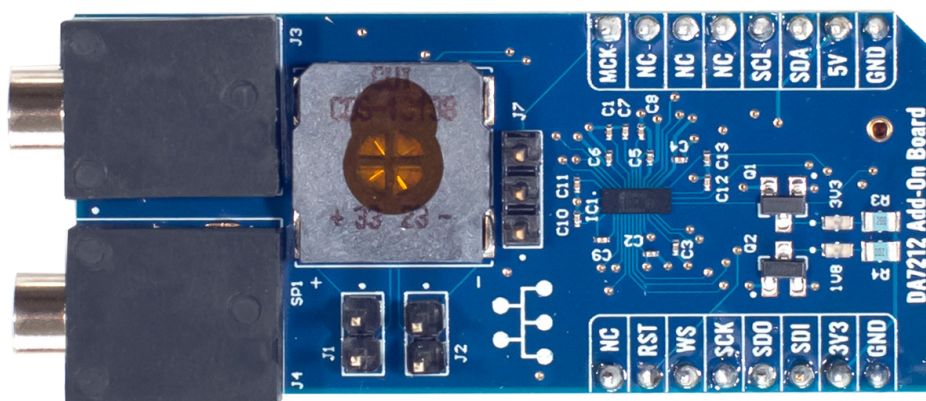


Figure 4. US082 ZSSC3123 Pmod Board Image (Top)

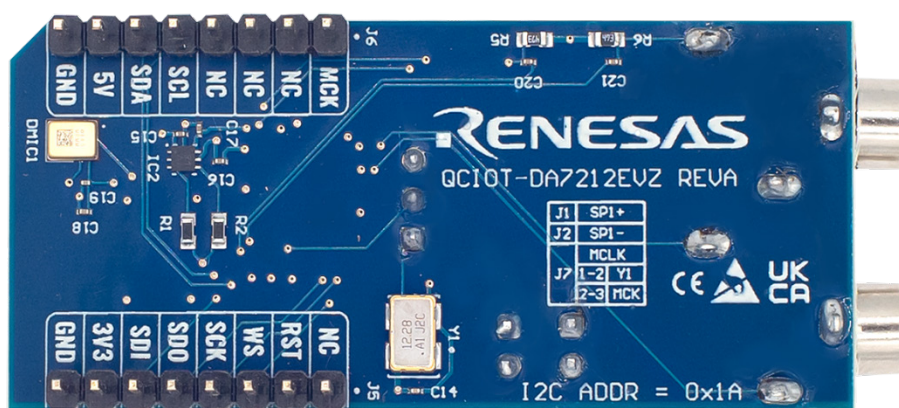
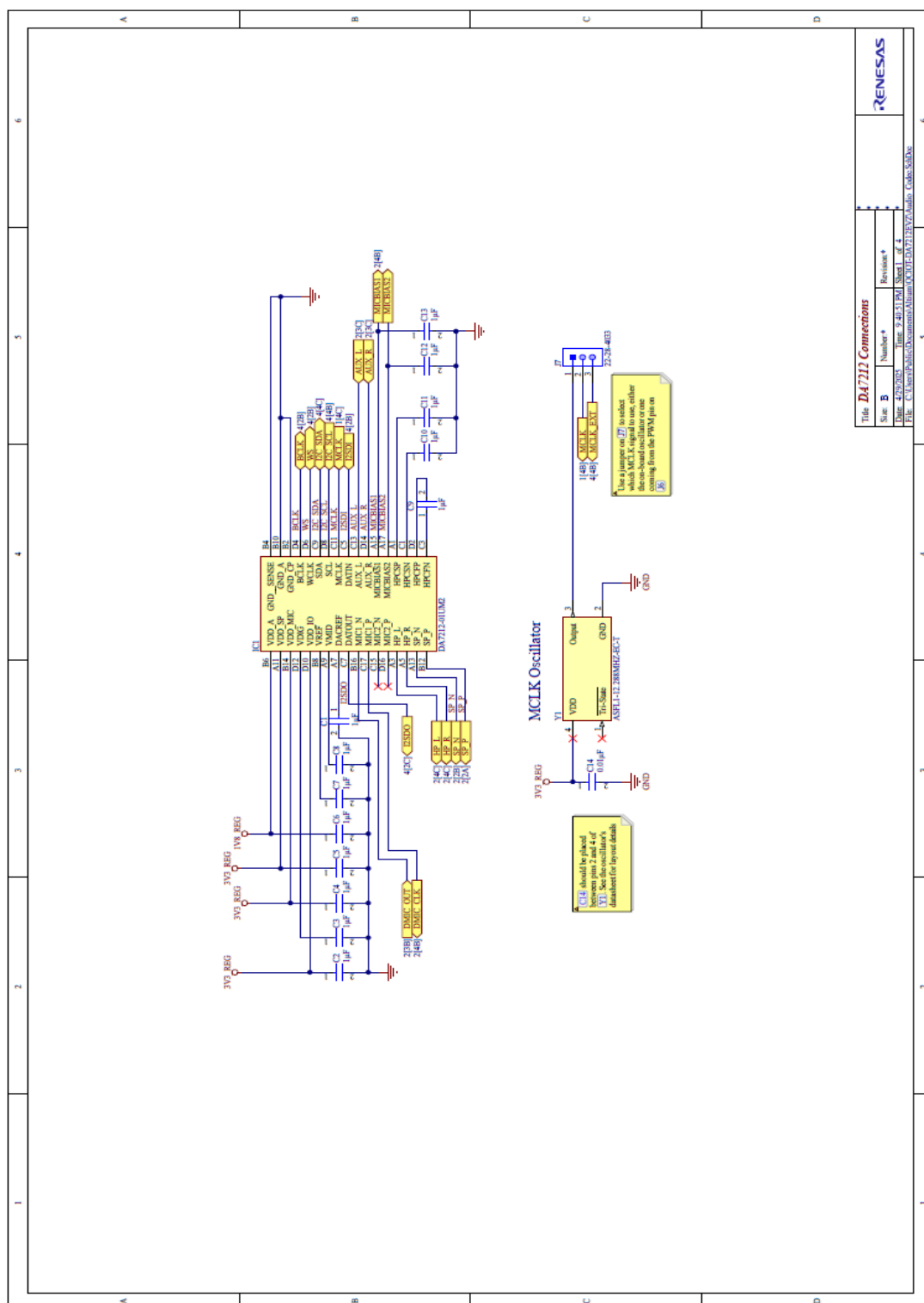


Figure 5. US082 ZSSC3123 Pmod Board Image (Bottom)

## 2.1 Schematic Diagrams



### Figure 6. DA7212 Connections Schematic

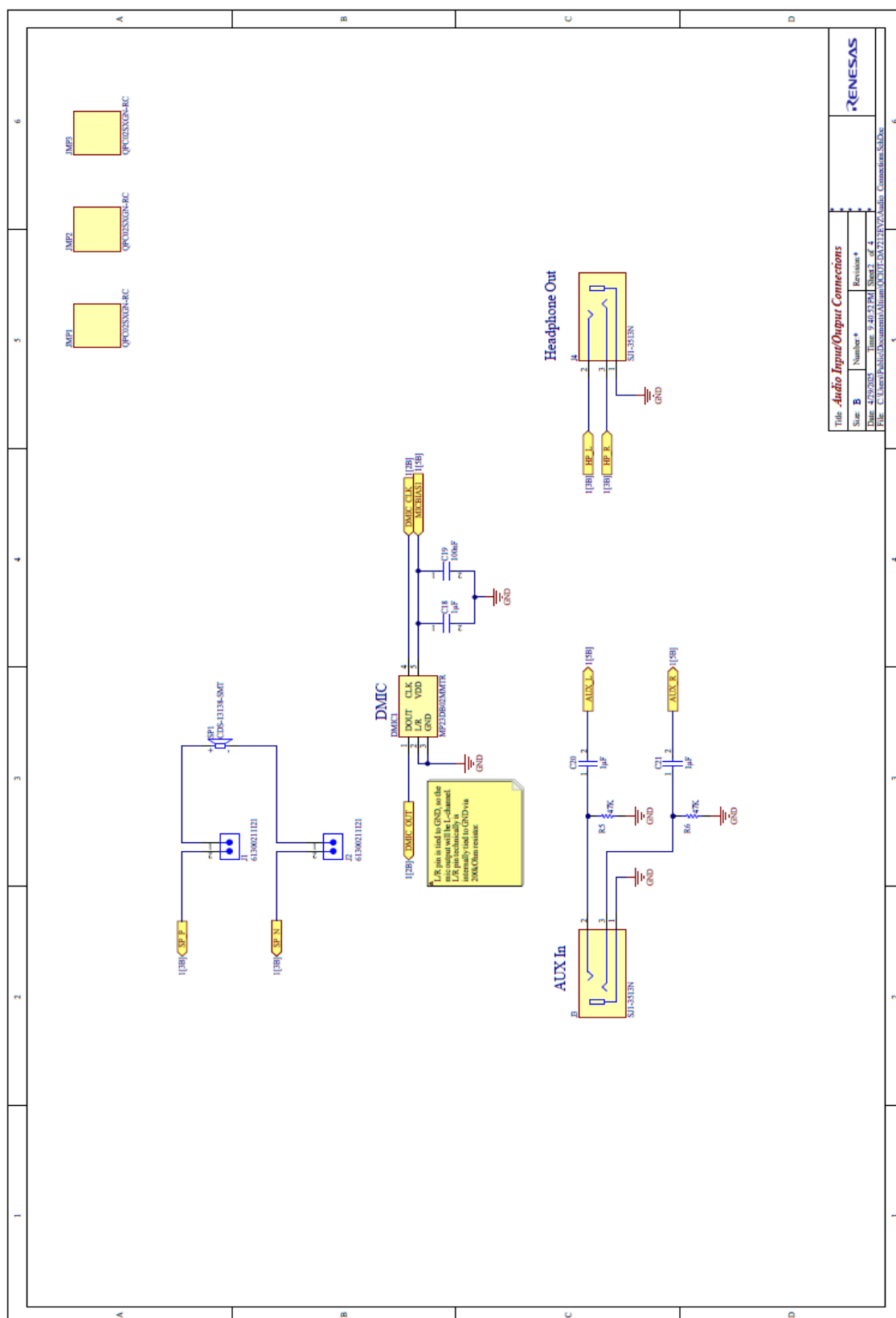
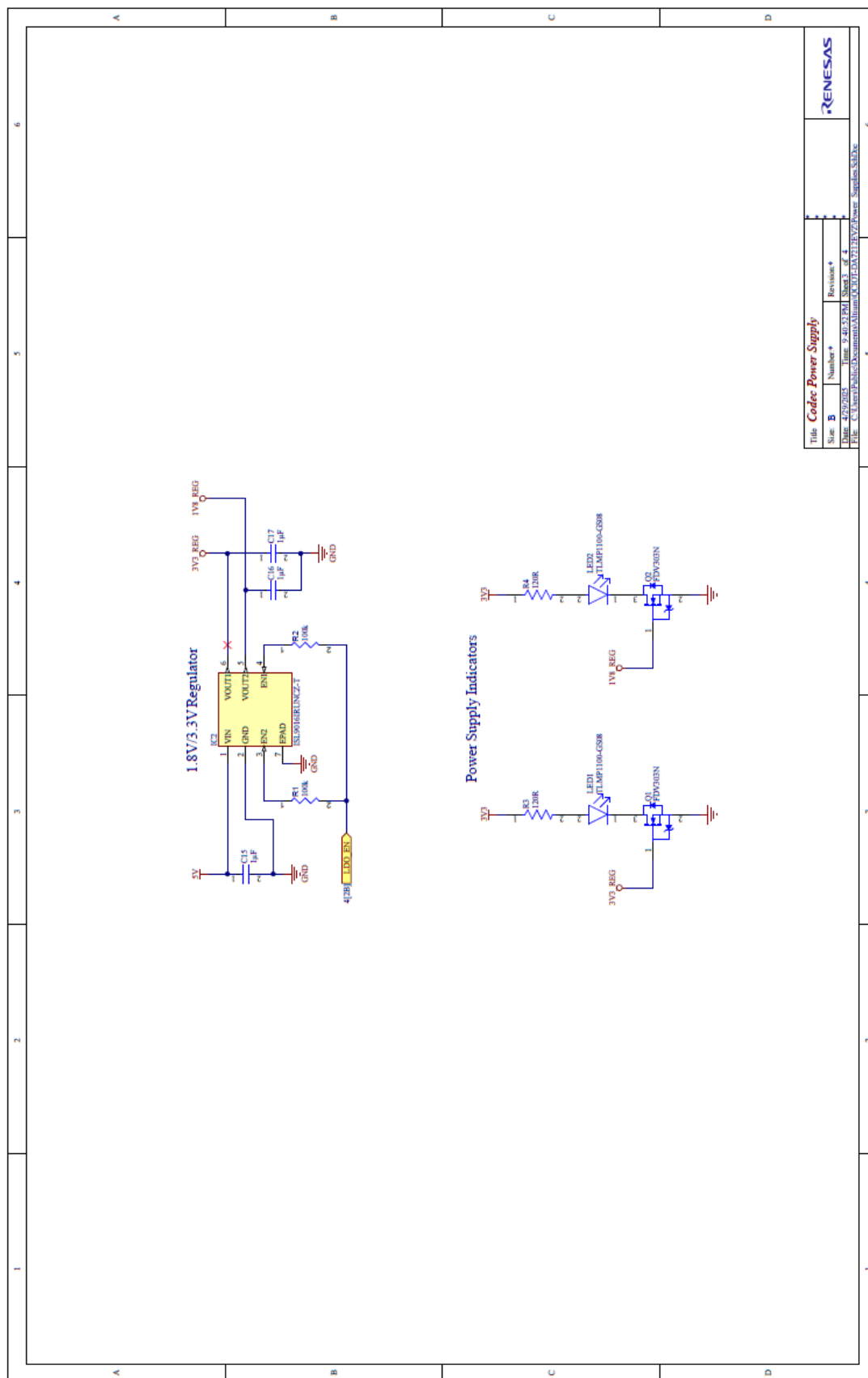
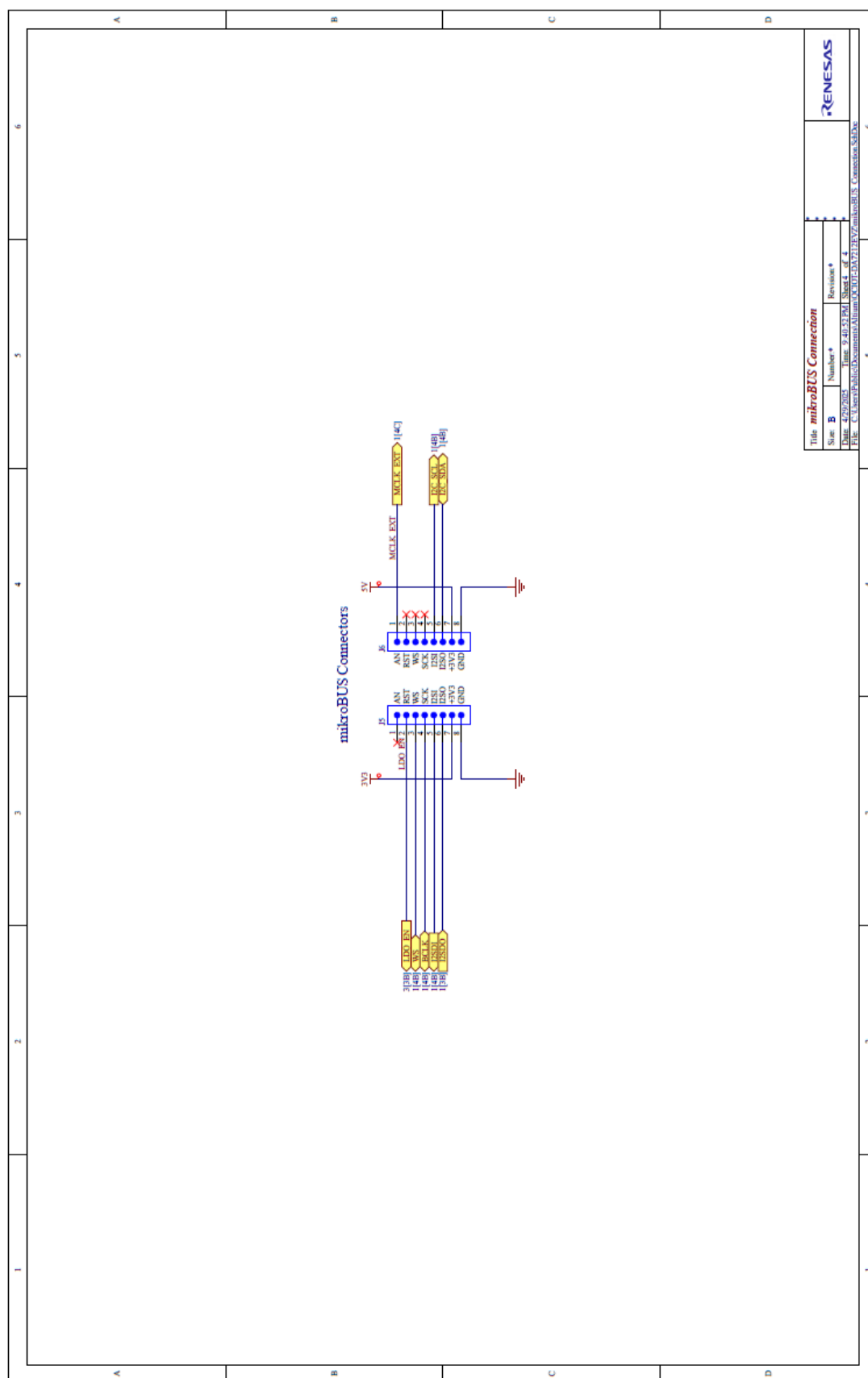


Figure 7. Audio Input/Output Connections Schematic



**Figure 8. Codec Power Supply Schematic**



### Figure 9. mikroBUS Connection Schematic

## 2.2 Bill of Materials (BOM)

| Qty | Reference Designator                                                                 | Description                                                                                              | Manufacturer                 | Manufacturer Part Number |
|-----|--------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------|------------------------------|--------------------------|
| 19  | C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C13, C15, C16, C17, C18, C20, C21 | Chip Multilayer Ceramic Capacitors for General Purpose, 0201, 1.0μF, X5R, 15%, 20%, 6.3V                 | Murata                       | GRM033R60J105MEA2D       |
| 1   | C14                                                                                  | Chip Multilayer Ceramic Capacitors for General Purpose, 0201, 10000pF, X7R, 15%, 10%, 10V                | Murata                       | GRM033R71A103KA01D       |
| 1   | C19                                                                                  | Chip Multilayer Ceramic Capacitors for General Purpose, 0201, 0.10μF, X5R, 15%, 10%, 6.3V                | Murata                       | GRM033R60J104KE19D       |
| 1   | DMIC1                                                                                | Integrated circuit                                                                                       | STMicroelectronics           | MP23DB02MMTR             |
| 1   | IC1                                                                                  | Integrated circuit                                                                                       | Dialog Semiconductor         | DA7212-01UM2             |
| 1   | IC2                                                                                  | ISL9016IRUNCZ-T Pb-free Dual Ldo W/low Noise, High Psrr, Low Iq 1.6 × 1.6 Ut                             | Renesas                      | ISL9016IRUNCZ-T          |
| 2   | J1, J2                                                                               | Conn Header Vert 2 Pos 2.54mm                                                                            | Würth Electronics            | 61300211121              |
| 2   | J3, J4                                                                               | 3.5 mm, Stereo, Right Angle, Through Hole, 3 Conductors, 0–2 Internal Switches, Audio Jack Connector     | Same Sky                     | SJ1-3513N                |
| 2   | J5, J6                                                                               | THT Vertical Pin Header WR-PHD, Pitch 2.54mm, Single Row, 8 pins                                         | Würth Electronics            | 61300811121              |
| 1   | J7                                                                                   | Male Header, Pitch 2.54 mm, 1 × 3 Position, Height 8.38mm, Tail Length 3.18mm, RoHS, Bulk                | Molex                        | 22-28-4033               |
| 3   | JMP1, JMP2, JMP3                                                                     | Conn Jumper Shorting .100" Gold                                                                          | Sullins                      | QPC02SXGN-RC             |
| 2   | LED1, LED2                                                                           | LED Green 0603 SMD                                                                                       | Vishay                       | TLMP1100-GS15            |
| 2   | Q1, Q2                                                                               | N-Channel MOSFET Transistor, 8 V VGSS, 25 V VDSS, 0.68A, -55 to 150 °C, 3-Pin SOT23, RoHS, Tape and Reel | ON Semiconductor / Fairchild | FDV303N                  |
| 2   | R1, R2                                                                               | Chip Resistor, 100 kOhm, ±1%, 0.1 W, -55 to 155 °C, 0603 (1608 Metric)                                   | Vishay                       | CRCW0603100KFKEAC        |
| 2   | R3, R4                                                                               | RES Thick Film, 120Ω, 1%, 0.125W, 100ppm/°C, 0805                                                        | Vishay                       | CRCW0805120RFKEA         |
| 2   | R5, R6                                                                               | Chip Resistor, 47 KOhm, ±1%, 0.1 W, -55 to 155 °C, 0603 (1608 Metric), RoHS, Tape and Reel               | Panasonic                    | ERJ-3EKF4702V            |
| 1   | SP1                                                                                  | 13 mm, Square Frame, 0.7 W, 8 Ohm, Samarium Cobalt Magnet, Mylar Cone                                    | Same Sky                     | CDS-13138-SMT-TR         |
| 1   | Y1                                                                                   | XTAL Oscillator 12.288MHz ±50ppm HCMOS, TTL 3.3V 4-SMD 5mm × 3.2mm                                       | Abracon                      | ASFL1-12.288MHZ-EC-T     |

## 2.3 Board Layout

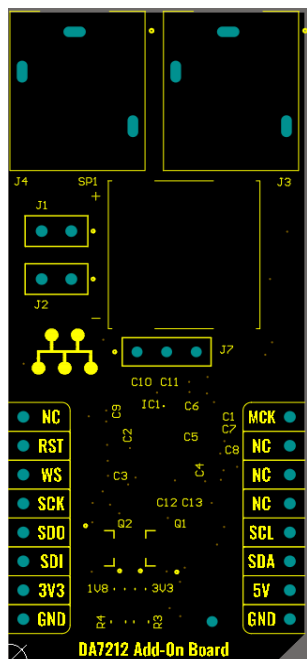


Figure 10. Top Overlay

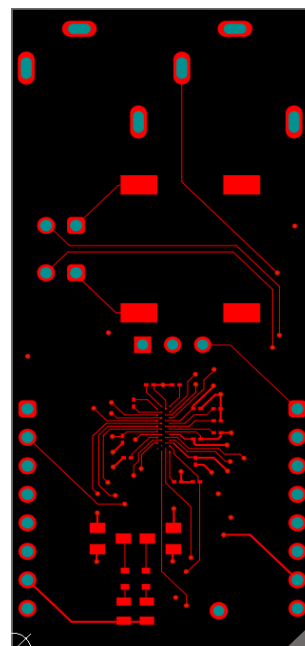


Figure 11. Top Layer

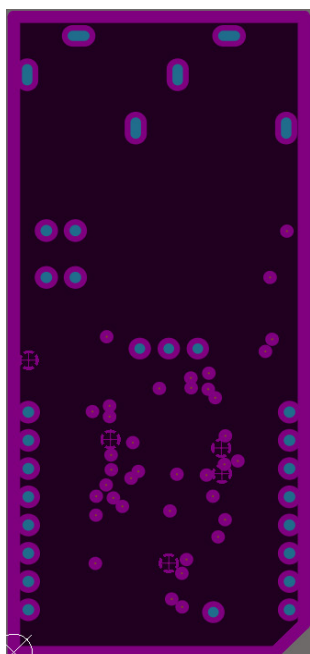


Figure 12. Layer 2 (GND)

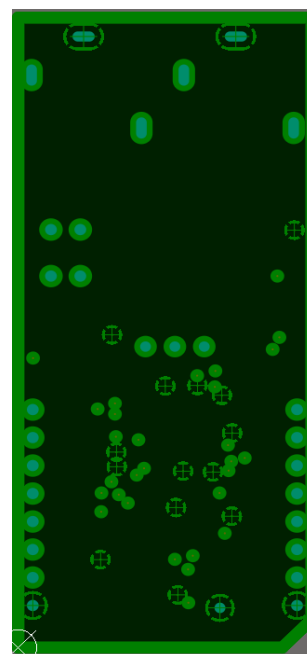


Figure 13. Layer 3 (3V3)

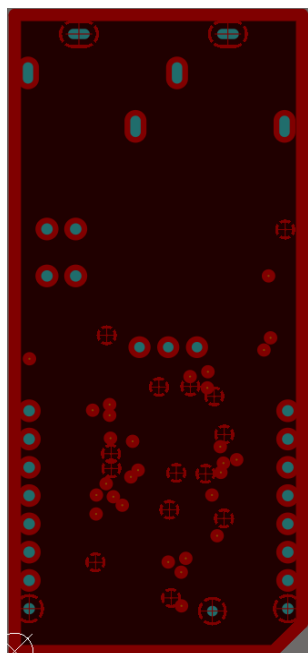


Figure 14. Layer 4 (1V8)



Figure 15. Layer 5 (GND)

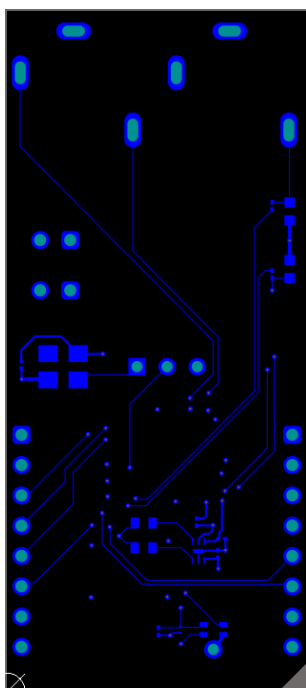


Figure 16. Bottom Layer

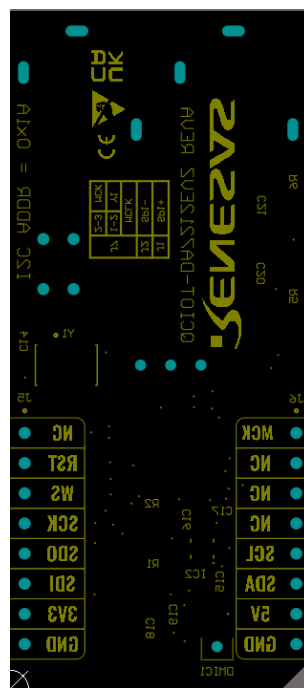


Figure 17. Bottom Overlay

### 3. Software Design

The following sections present an overview of the software implementation and detail the project's code structure, the system's software modules, and the main system flow for the QCIOT-DA7212EVZ Click board. This is based on the Renesas RA Family's Flexible Software Package (FSP).

The provided demo sets the mikroBUS Reset pin to high to enable the LDO on the QCIOT-DA7212EVZ Click board on start-up and uses **audio\_codec\_init** routine to initialize the QCIOT-DA7212EVZ Click board for audio input/output handling.

The **fie\_initFileSystem** routine initializes the FAT FS for media access and initializes the cyberon Dspotter engine. The **voice\_main** routine is responsible for processing the user voice input using the on-board microphone and for playing audio either on the on-board speaker or via headphone.

For more information on software design, refer to the QCIOT-DA7212EVZ application note.

#### 3.1 Project Code Structure

The Quick Connect project is designed to be a highly modular solution that can be easily configured independently of other modules (if required) or ported to other end applications.

Figure 18 shows the structure of the project in e<sup>2</sup> studio.

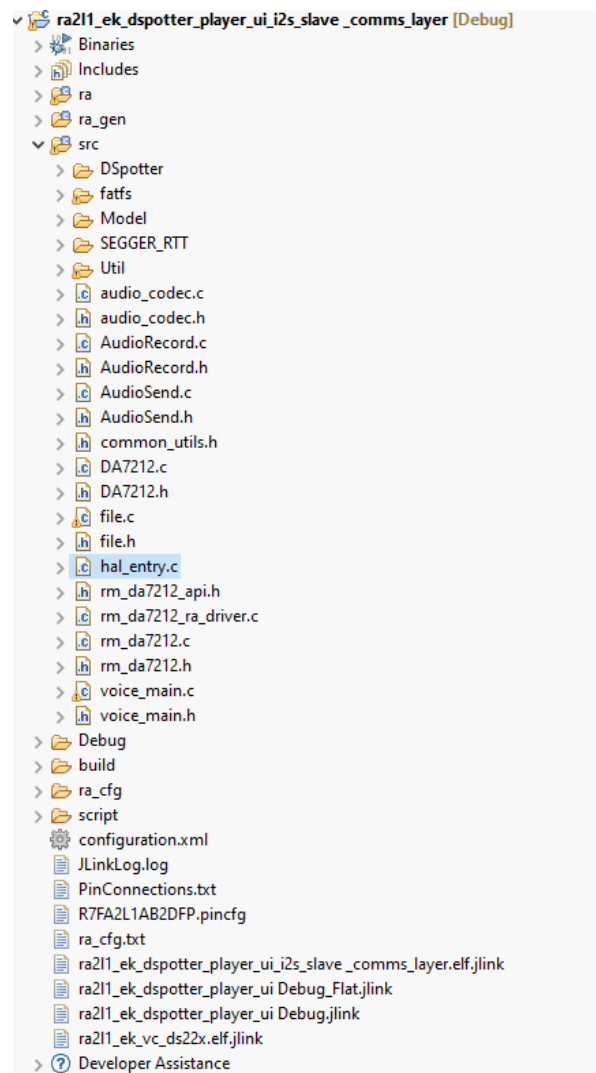


Figure 18. Project Structure

## 4. Board Test

### 4.1 Run Code in Stand-Alone Mode

1. Before loading the sample project to the MCU, ensure the SD card contains loaded music files.

*Note:* The music files should be formatted as **.wav** files, channels should be set to Mono, and the sample rate should be 16kHz. The [Audacity](#) tool is used to export audio.

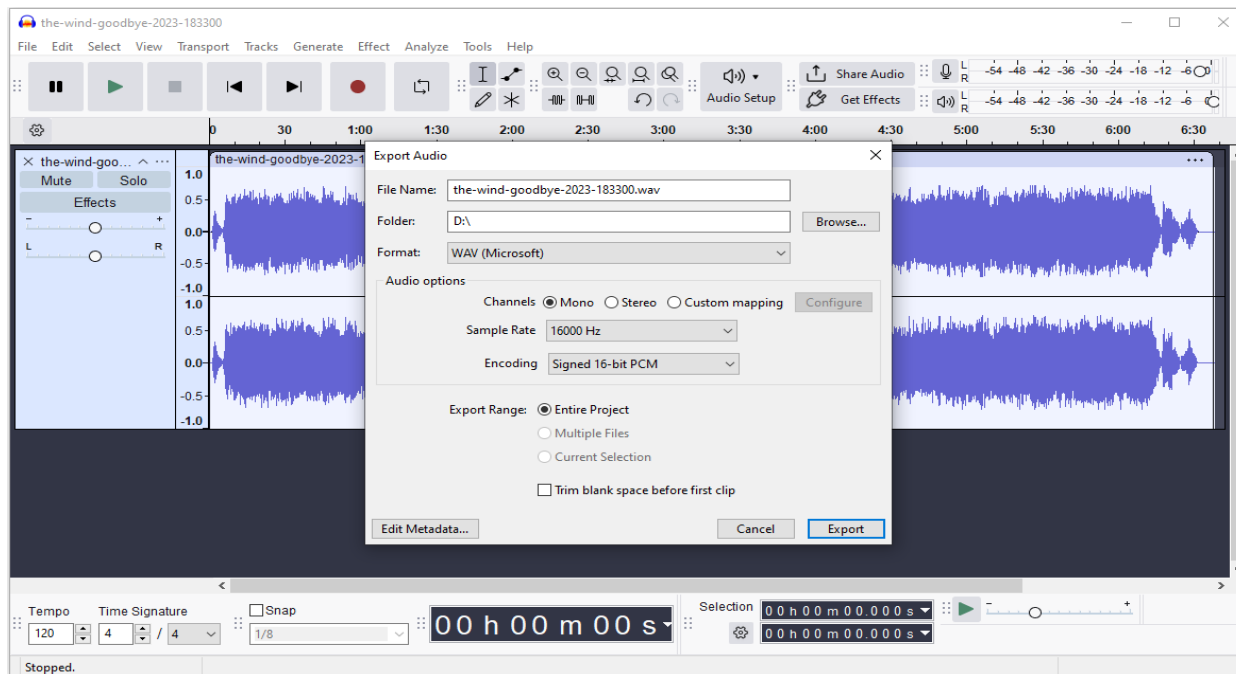


Figure 18. Audio File Format

2. Build the sample code in e<sup>2</sup> studio to generate the **.srec** file under the Debug folder

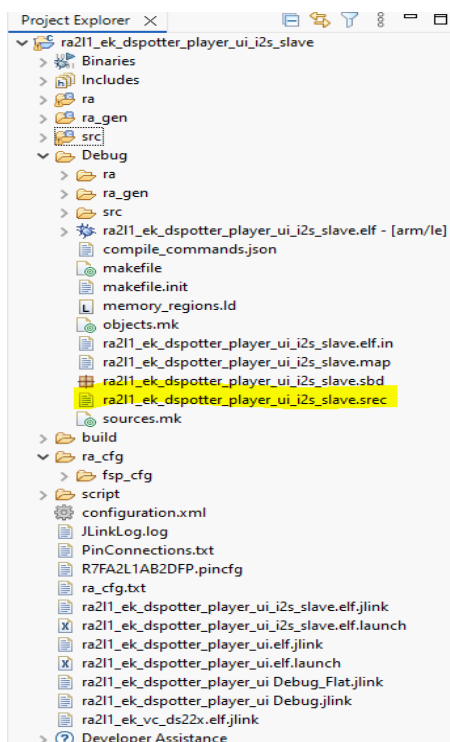


Figure 19. Generated .srec File

- Load the .srec file to the EK-RA2L1 MCU using the [SEGGER J-Flash Lite](#) tool.

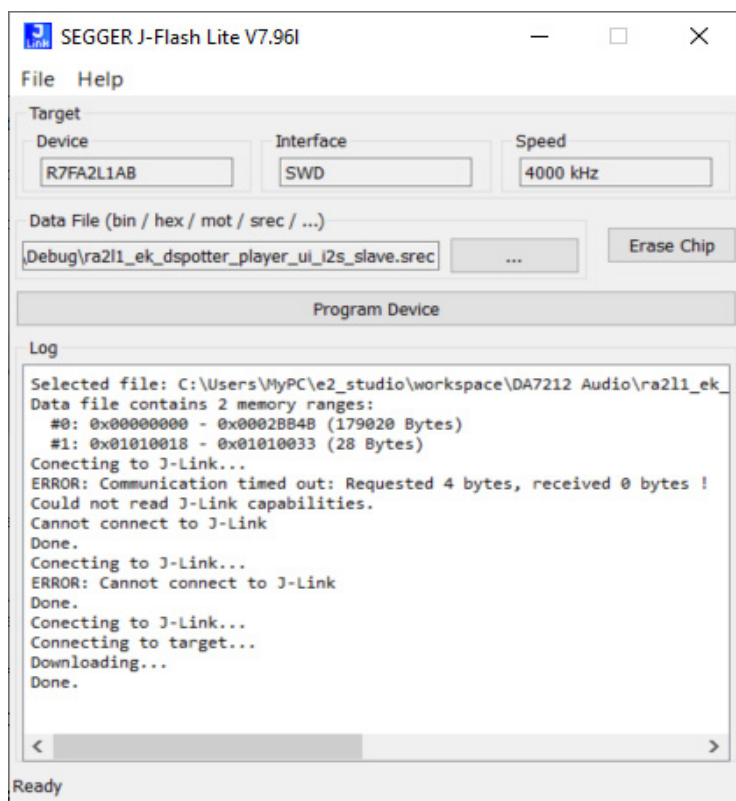


Figure 20. SEGGER J-Flash Lite Tool

- Connect the USB to TTL. On the EK-RA2L1, connect RXD to P302, TXD to P301, and GND to GND.
- Open PuTTY and select the appropriate correct COM port. Change the Speed (baud) rate to 115200.

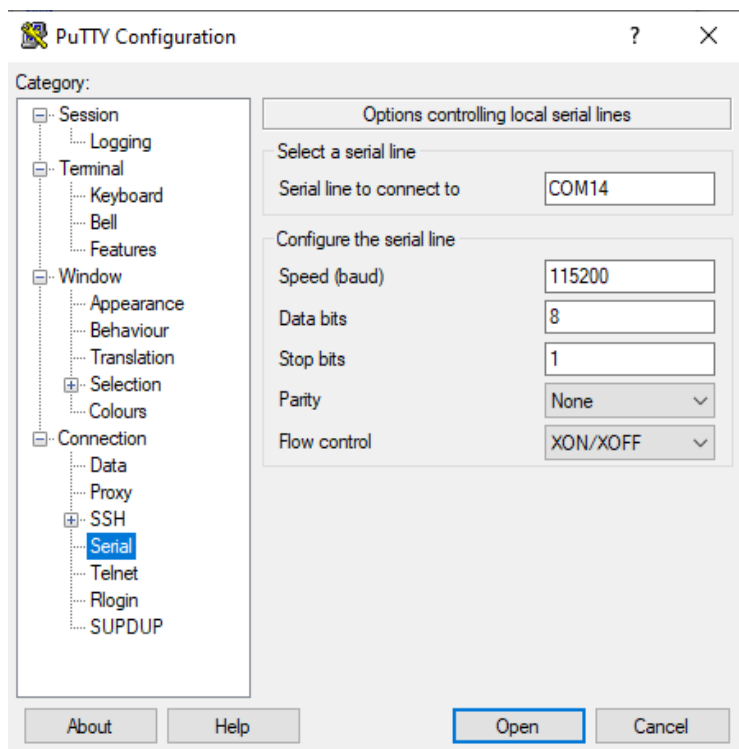


Figure 21. PuTTY Settings

6. Connect the 5V power supply to TP7 and GND to TP 9 on the EK-RA2L1. Switch on power supply. Ensure the following message is displayed on PuTTY as shown in [Figure 22](#).

COM14 - PuTTY

```

Little Endian
MCU board: RA2L1_EK
FSP version: 4.5
Dspotter version: DspotterSDK Release v2.2.14.1 (compiled at Mar 25 2022)
Copyright (C) 2018-2022 Cyberon Corp.
Sample code build: 220325
Unique ID: 0x36021738-37383030-D9453339-4B5728D6
The Dspotter declare memory buffer size = 20416
The model group 0 needed working memory size = 20416
The command list of group index 0:
  Play Music, Map ID = 101
  Stop Music, Map ID = 102
  Pause Music, Map ID = 103
  Next Track, Map ID = 104
  Previous Track, Map ID = 105

Wake-up group active.
  Play Music, Map ID = 101
  Stop Music, Map ID = 102
  Pause Music, Map ID = 103
  Next Track, Map ID = 104
  Previous Track, Map ID = 105

```

Figure 22. UART Output

7. Press switch S1 on EK-RA2L1 to run Cyberon-Dspotter. Say "Play music" to start playing music using the on-board speaker.
8. Press Switch S1 on EK-RA2L1. Say "Next track" to switch to the next track.

COM14 - PuTTY

```

Little Endian
MCU board: RA2L1_EK
FSP version: 4.5
Dspotter version: DspotterSDK Release v2.2.14.1 (compiled at Mar 25 2022)
Copyright (C) 2018-2022 Cyberon Corp.
Sample code build: 220325
Unique ID: 0x36021738-37383030-D9453339-4B5728D6
The Dspotter declare memory buffer size = 20416
The model group 0 needed working memory size = 20416
The command list of group index 0:
  Play Music, Map ID = 101
  Stop Music, Map ID = 102
  Pause Music, Map ID = 103
  Next Track, Map ID = 104
  Previous Track, Map ID = 105

Wake-up group active.
  Play Music, Map ID = 101
  Stop Music, Map ID = 102
  Pause Music, Map ID = 103
  Next Track, Map ID = 104
  Previous Track, Map ID = 105

.
Get command(0) : Play Music, Score=30, SG_Diff=93, Energy=446, MapID=101
...
Get command(9) : Next Track, Score=56, SG_Diff=151, Energy=900, MapID=104

```

## 5. Ordering Information

| Orderable Part Number | Description        |
|-----------------------|--------------------|
| QCIOT-DA7212EVZ       | DA7212 Click Board |

## 6. Revision History

| Revision | Date        | Description      |
|----------|-------------|------------------|
| 1.00     | Jun 9, 2025 | Initial release. |

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